

# **32 Channel ASICs for Detector Signal Digitizing and Processing**

**SBIR Awards: DE-SC0017213  
DE-SC0018566**

Dalius Baranauskas  
Anton Karnitski  
Reza Ramezani  
Gytis Baranauskas

# Presentation Outline



- The Company, Its Specialization/Expertise
- ASIC Development Motivation
- Relevance to the NP Program
- Project Goals
- **ASIC #1** - 12-bit 32 Ch 500MS/s ADC
- Chip Specifications and Architecture
- Comparison to ADCs Available on the Market
- Chip Carrier and Packaging
- Testing Results
- Future Plans
- **ASIC #2** – Event Driven Backen with 12-bit 32 Ch 200MS/s ADC
- Chip Specifications and Architecture
- Digital Backend Implementation
- Chip and Its Packaging
- Testing Results
- Future Plans

# The Company

- **Pacific MicroCHIP Corp. was incorporated in 2006.**
- **It is headquartered in Culver City, California.**
- **Main focus of the Company – providing IC/ASIC design services and turnkey solutions.**



**Office in Culver City, CA**

# Our Offerings



## IC/ASIC Design Services:

- **Circuit Design (analog, RF/mixed, digital)**
- **Simulation**
- **Physical Design**
- **Chip Assembly**

## Turnkey Solutions:

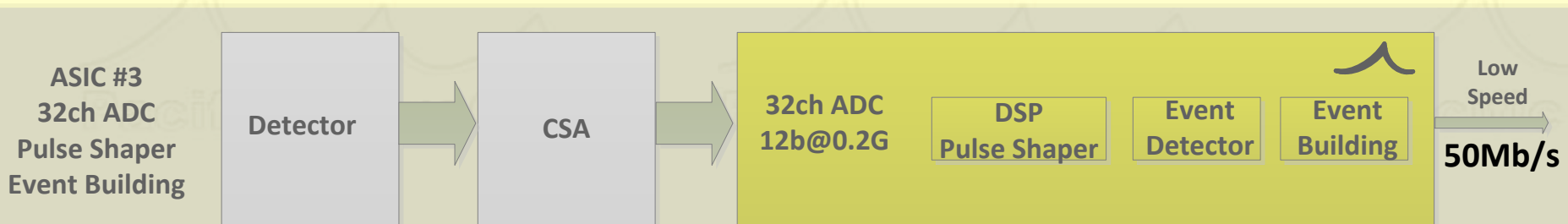
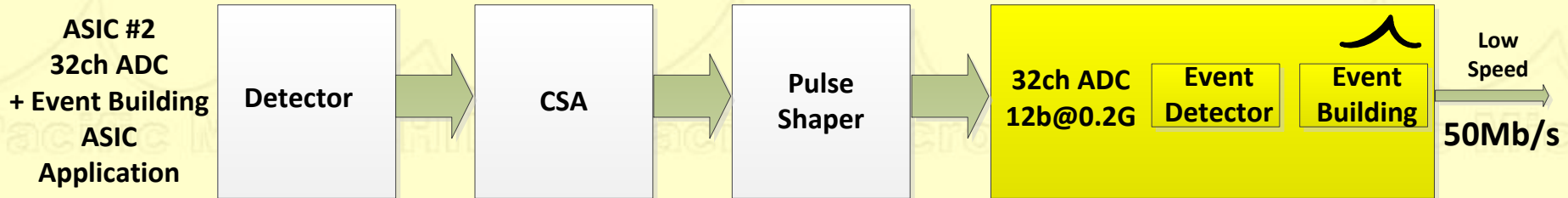
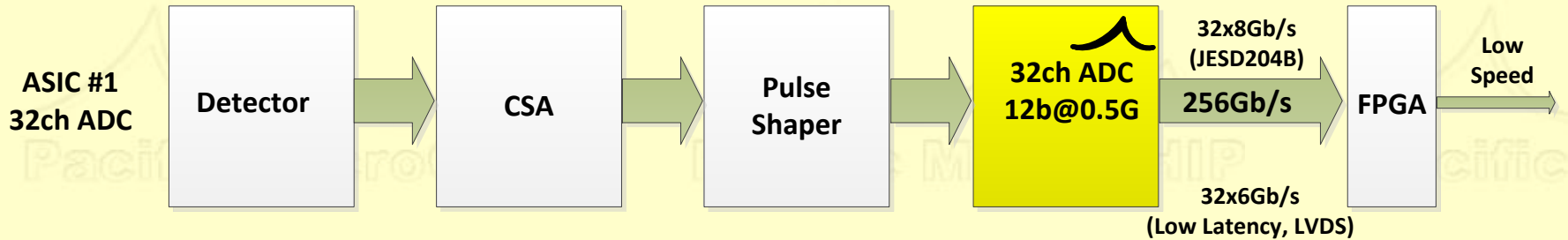
- **ASIC Design**
- **Chip Fabrication Logistics**
- **Package Development (involving a 3<sup>rd</sup> party)**
- **Chip Packaging (involving a 3<sup>rd</sup> party)**
- **PCB Development for Testing/Eval. (involving a 3<sup>rd</sup> party)**
- **Testing/Characterization (an in-house lab)**
- **Delivery of Chips, Parts and Board Level Solutions**

# **SBIR Funded Development of ASICs for Detector Signal Processing**

**ASIC #1: 32 Ch 12-bit 0.5GS/s ADC**

**ASIC #2: 32 Ch 12-bit 0.2GS/s ADC + Event  
Driven Back-end**

# Where the ASICs Fit



DoE SBIR proposal rejected at administrative screening as “state-of-the-art is not being advanced” ☹



# Relevance to the NP Needs

**Modern detectors include thousands of signal processing channels**

**Need for digitizing channels to:**

- Shrink in size – our ASICs combine 32 independent ADCs per chip.
- Reduce power consumption – 25mW (ASIC #1), 6mW (ASIC #2) per channel.
- Reduce wire congestion:
  - . ASIC #1 and ASIC #2 – a serial interface can be shared between 2, 4 or 8 ADCs.
  - . ASIC #2 – Event Driven Back-end greatly reduce interface data rate.

**Other requirements:**

- Digitizing accuracy - our ADC features 12-bit resolution.
- Adequate sampling speed - our ADC features up to 0.5GS/s (ASIC #1).
- Low conversion latency - we offer down to 8ns (ASIC #1).

# ASIC Development Project Goals

- **To design chips.**
- **To fabricate the chips.**
- **To develop a special chip carrier.**
- **To package the chips.**
- **To develop a test PCB and a DUT socket.**
- **To develop a GUI and a test bench.**
- **To test and characterize ASICs.**



# **ASIC #1**

## **12-bit 32 Channel 500MSps**

### **Low Latency ADC**

# ASIC #1

## 12-bit 32 Channel 500MSps

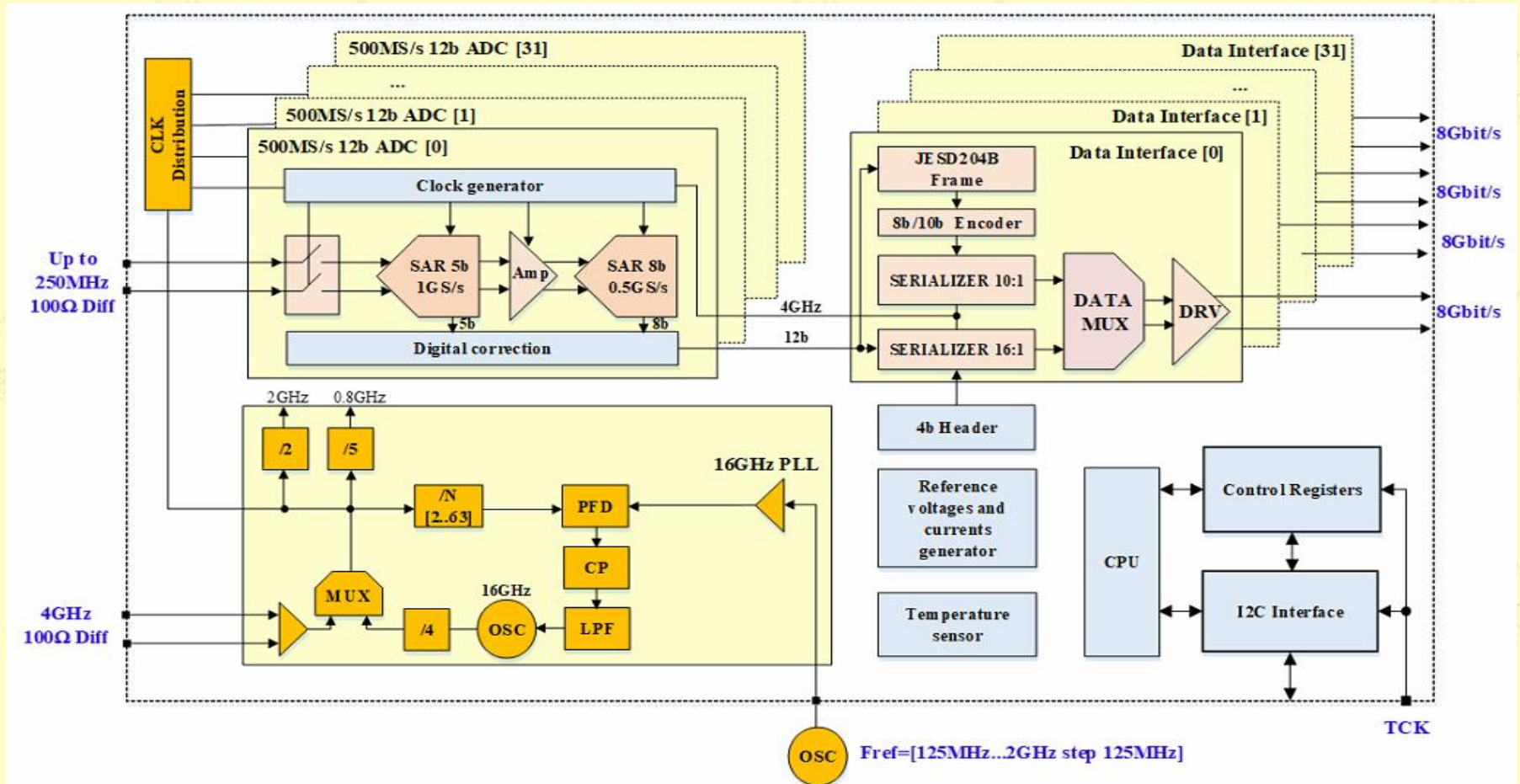
## Low Latency ADC

### Specifications (expected performance):

- 32 independently operated ADC channels
- 500 MS/s sampling rate
- 0.6Vpp differential input swing
- 10-bit ENOB
- 250MHz input signal bandwidth
- -40C..+125C temperature range
- 25mW/channel power consumption (with an interface)
- JESD204B output data interface
- 8ns latency (direct ADC data output mode)
- 32x8Gb/s output data rate
- I2C interface for ASIC control
- 7.7mm<sup>2</sup> ASIC layout footprint
- A solder bumped die in a BGA package
- 28nm CMOS technology

# 12-bit 32 Channel 500MSps Low Latency ADC

## ASIC Block Diagram



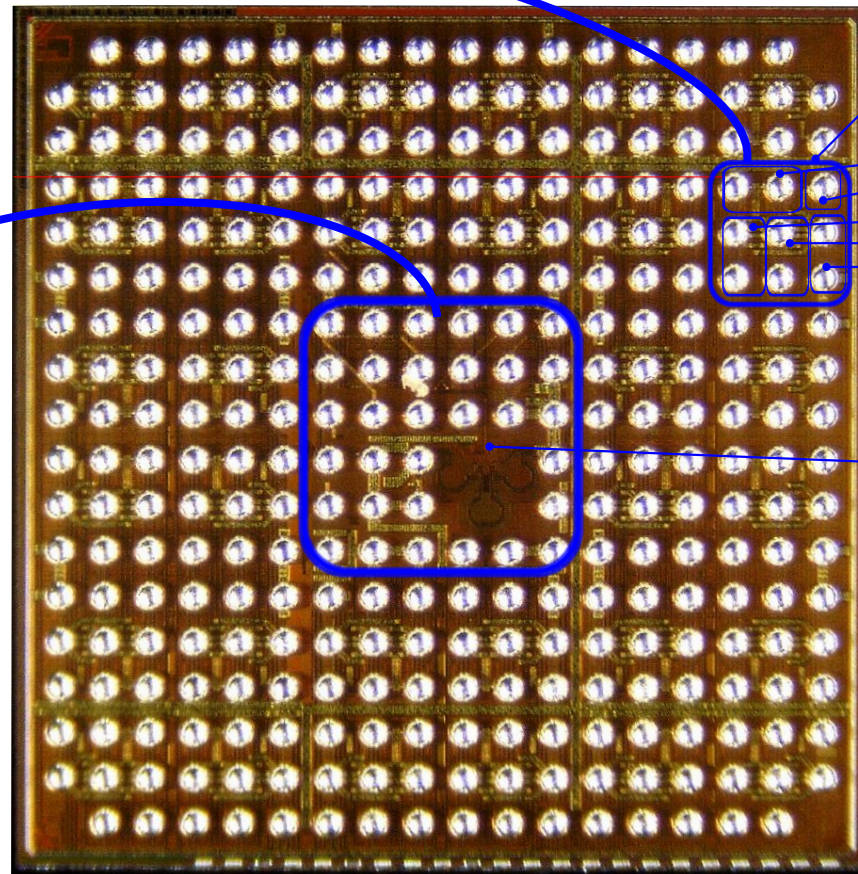
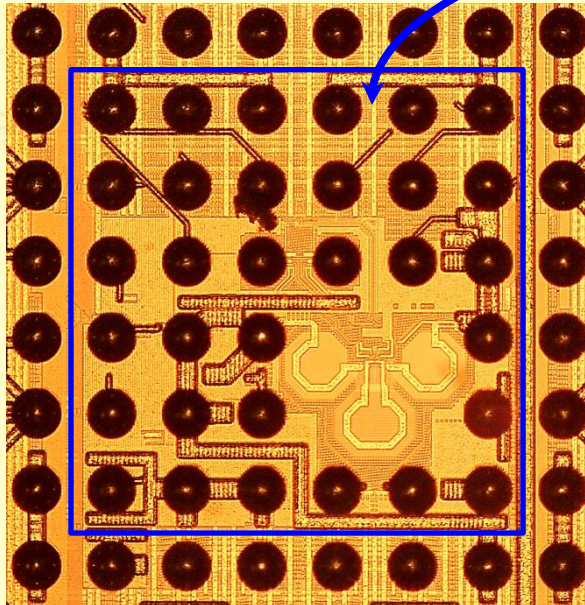
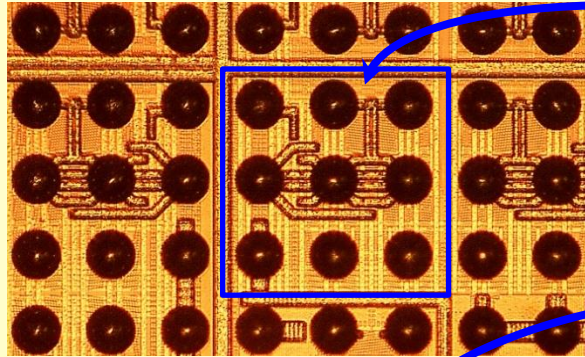
# Comparison to ADCs Available on the Market

#	Vendor	# of Channels	Sample Rate, MS/s	Power Cons. per Channel	Architecture & Latency
1.	TI 12-bit ADS52J90	32	40	41mW	Pipeline 2.5us
2.	TI 12-bit ADS5403IZAYR	1	500	1W	Pipeline 240ns
3.	TI 12-bit ADS54T04IZAYR	2	500	1.15W	Pipeline 240ns
4.	ADI 12-bit AD9234BCPZRL7	2	500	1.5W	Pipeline 240ns
5.	Pacific Microchip Corp. 12-bit*	32	500	25mW	SAR/Pipeline 8ns

\* Expected performance



# Fabricated Chips



ADC Channel  
(1 out of 32)

Output Data Buffer  
Digital Registers

Sub-ADC1  
Sub-ADC2  
Offset Cancellation

Common Block With:  
• PLL  
• Temperature Sensor  
• CPU for Calibration  
• I2C Control Interface



# Chip Packaging

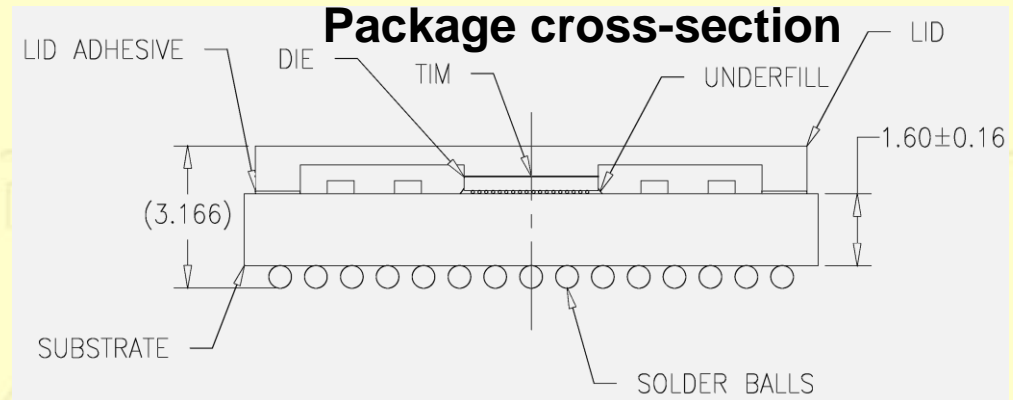
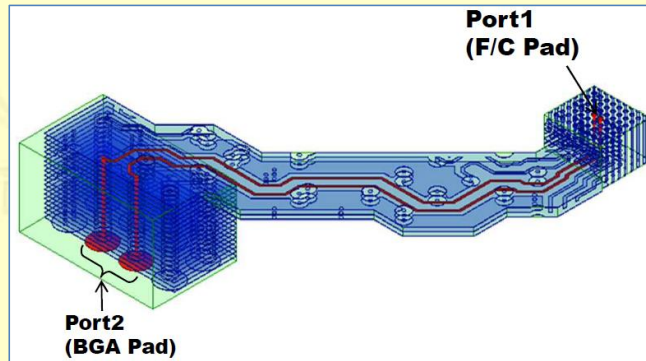
BGA 15.2 x 15.2 mm, 18 x 18 balls, 0.8mm ball pitch

## Package Design

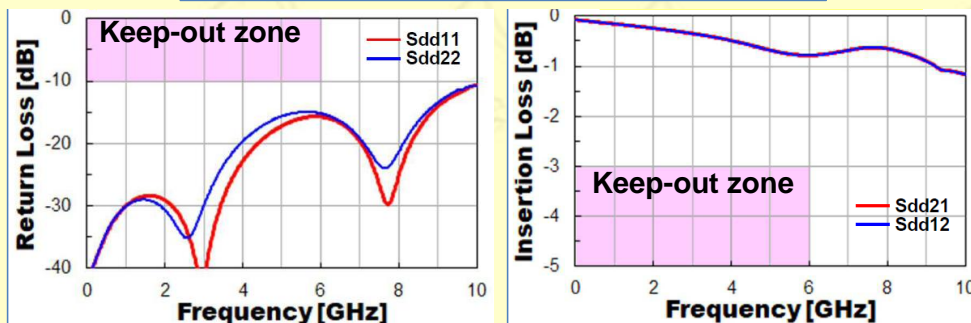
S-parameter simulation results for longest I/O wires:

$S_{11} < -10\text{dB}$  up to 10GHz

$S_{21} > -1\text{dB}$  up to 9GHz



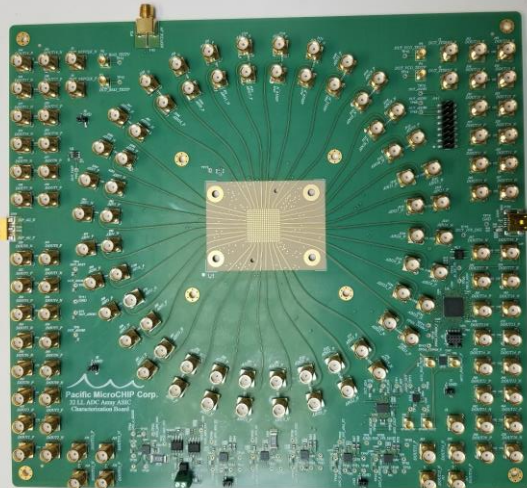
Packaged parts



# Testing Setup

## ← Test Board

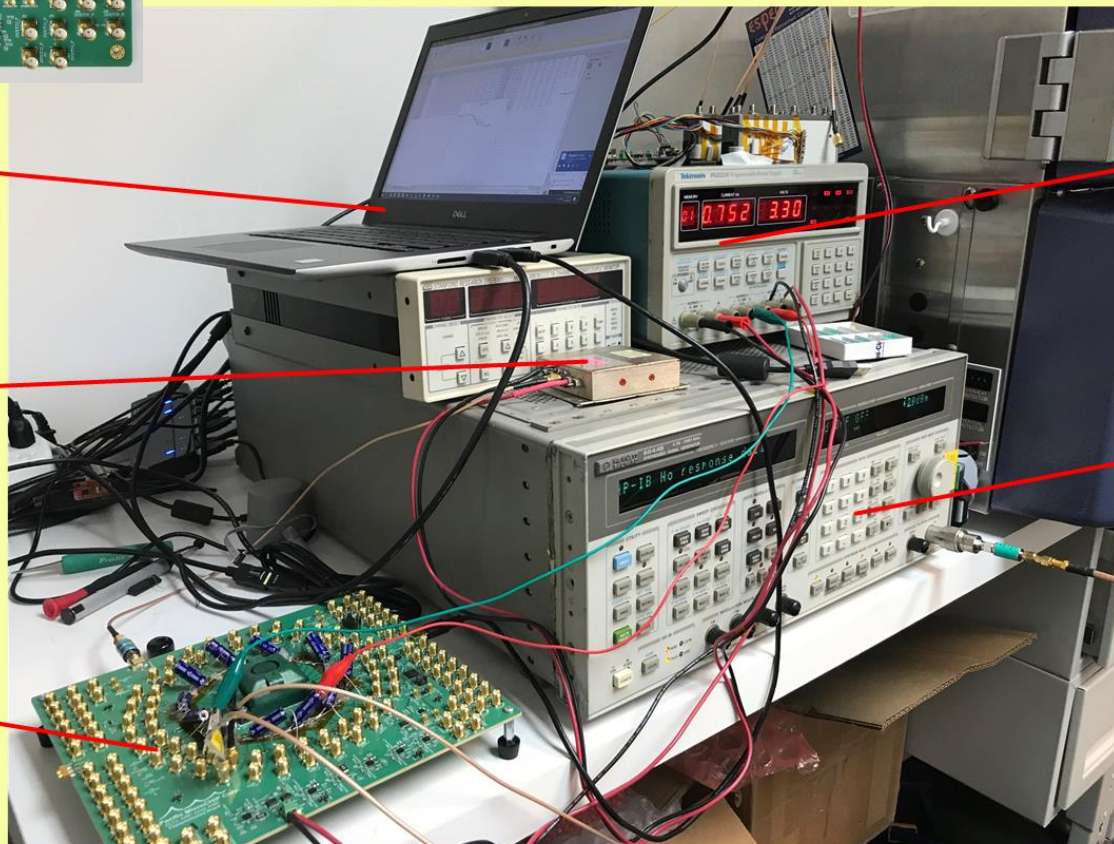
- Exposed area in the center for DUT socket
- 32 differential inputs in a circle for delay equalization
- 32 differential outputs at the PCB's edge (less critical to PCB losses)



Windows PC for  
controlling all  
equipment and  
characterization PCB

Ultra-low jitter 2GHz  
clock source

Characterization PCB



Power supply for  
powering board,  
clock generator and  
external VCM

HP8644B Ultra-low  
noise signal  
generator



# Preliminary Testing Results

## Power Consumption

Supply	V [Volts]	I [mA]	P [mW]
VDDD	0.9	445	400.5
VDD18	1.8	9	16.2
VDDA	0.9	88	79.2
VDD12	1.2	564	676.8
PLL	0.9	60	54.0
Total:			1226.7
Per Channel:			<b>38.3</b>

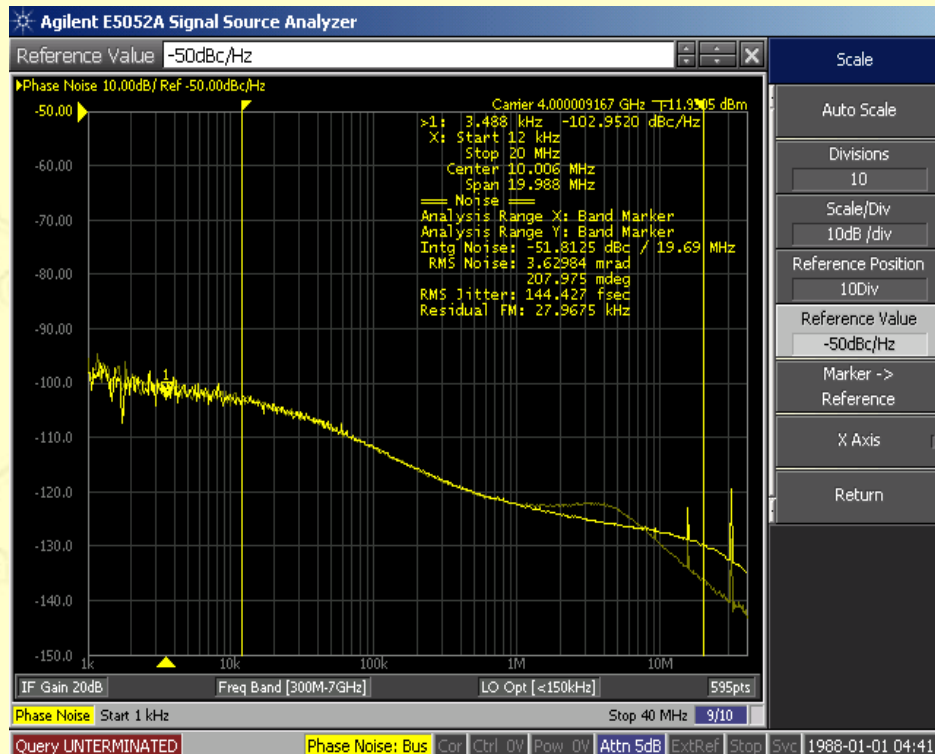
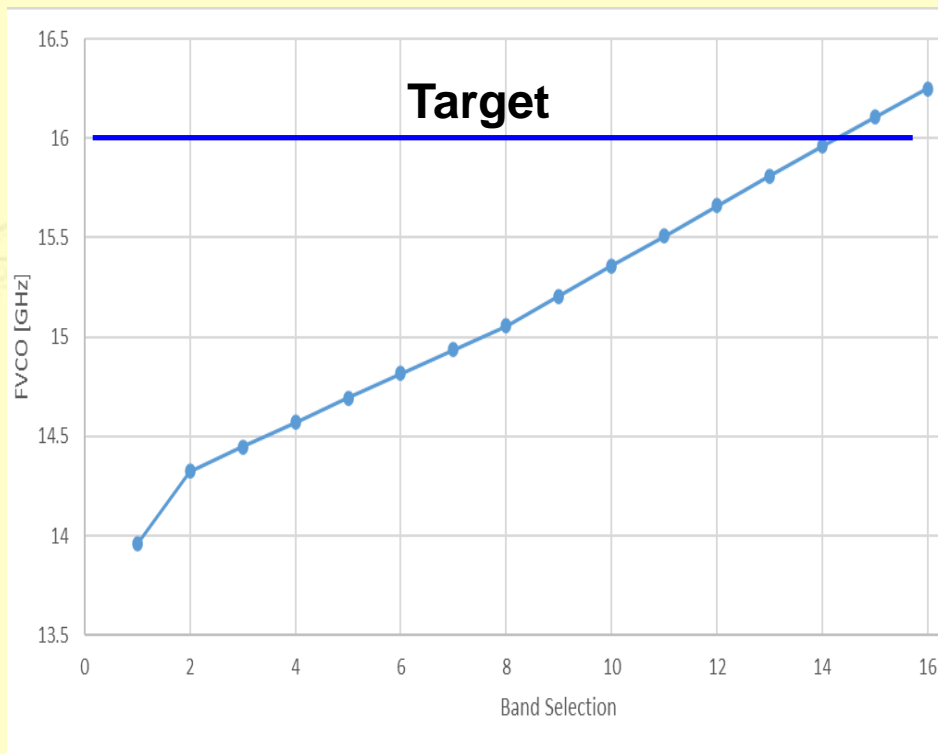
Notes: Power of the JESD204B interface is included. An input signal is applied only to a single ADC out of 32. The VDDD consumption is expected to increase when a signal is applied.

# Preliminary Testing Results

## PLL Performance

Targeted frequency achieved on the 14<sup>th</sup> band. It will be tuned up in the 2<sup>nd</sup> prototype.

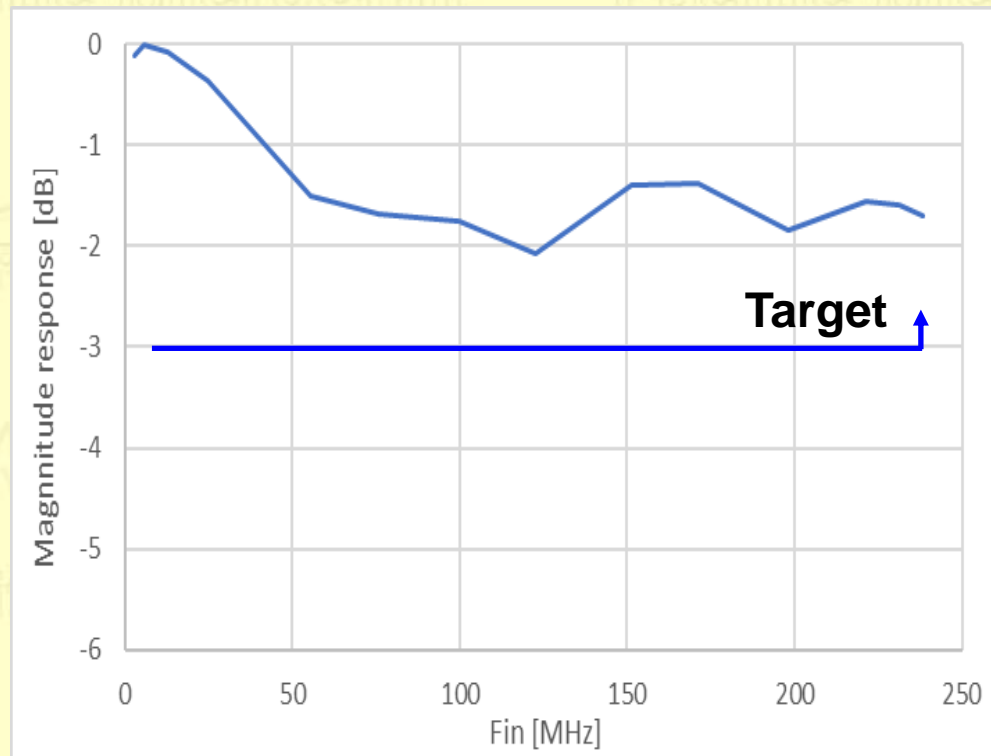
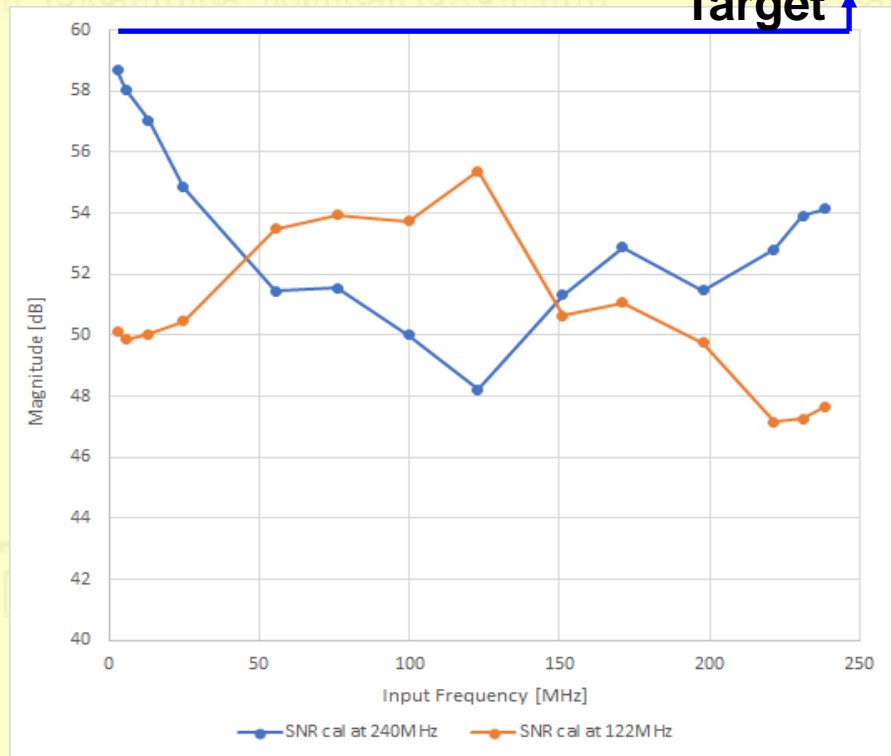
Phase noise tested at 16GHz/4.  
144fs RMS jitter (12K-20MHz range).  
Jitter does not depend significantly on PLL BW.



# Preliminary Testing Results

## ADC Performance

Target



## ENOB vs. Input signal frequency.

When the ADC is calibrated at 240MHz:

9.5 ENOB @ 5MHz

8.6 ENOB @ 250MHz (Nyquist)

When the ADC is calibrated at 122MHz:

8.8 ENOB @ 122MHz

# **Future Plans for ASIC #1**

- **To finish testing the chip's 1<sup>st</sup> prototype (End of Ph II).**
- **Transition to Phase IIB – to redesign the chip, increase its performance, fix issues identified during testing.**
- **To fabricate the final chip.**
- **To test/evaluate it.**
- **To prepare the chip description and datasheets.**
- **To organize the ADC ASIC design as an IP block and advertise it.**
- **To provide the chip to the DoE community and commercial customers.**

## **ASIC #2**

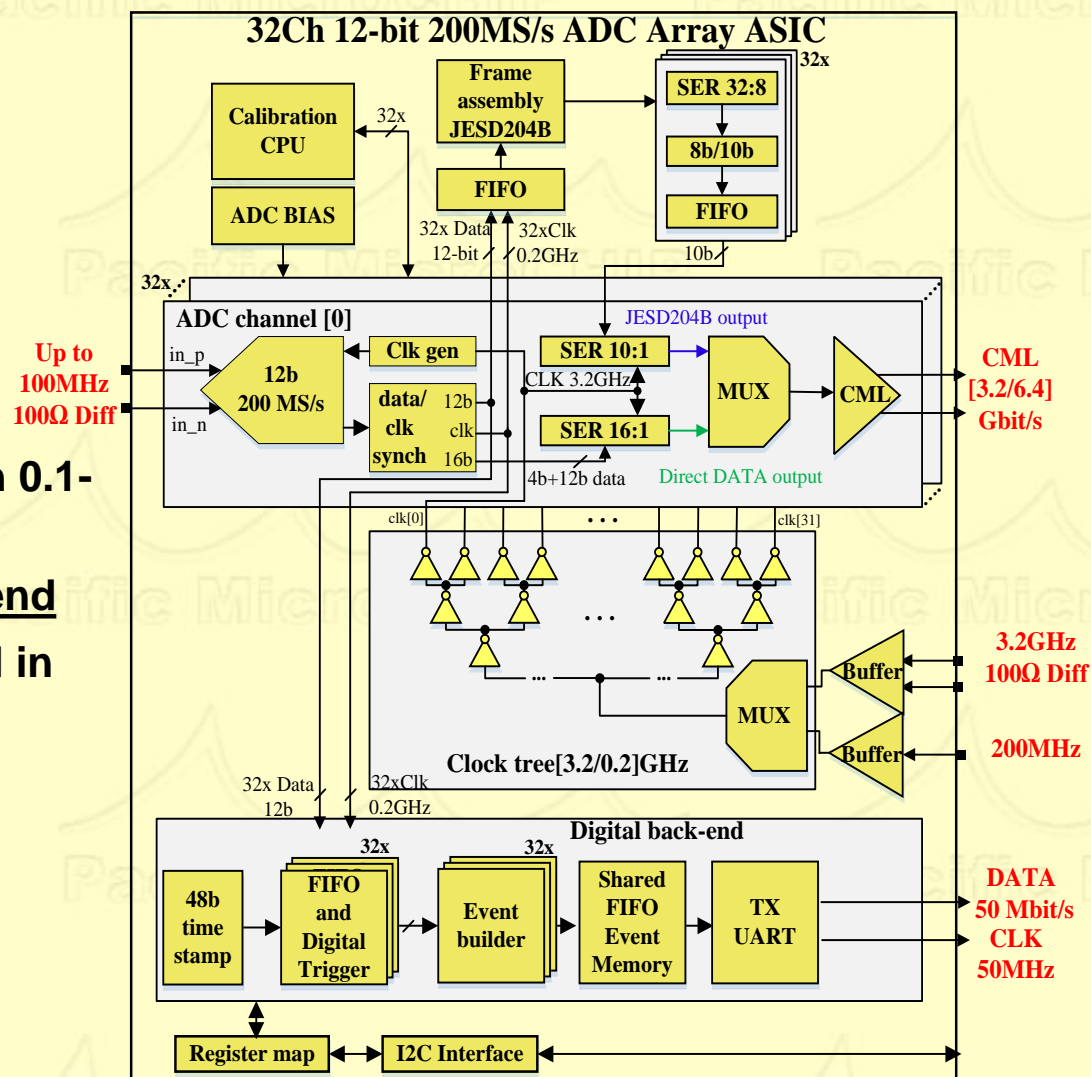
**12-bit 32 Channel 200MSps ADC**

**With Event Driven Back-end**

**(Digital part developed in collaboration with the LBNL)**

# ASIC #2 Specifications/Features

- 32 independent ADC channels
- Programmable sampling rate of 200/100/50 MS/s
- Synchronous clock/reset for 32 ADC channels
- ENOB > 10-bit
- 1Vpp differential input signal
- Programmable input signal bandwidth 0.1-0.3 GHz
- Integrated Event Driven Digital Back-end
- JESD204B output data interface (used in the ADC mode)
- Low power consumption  
5 mW / channel (w/o interface)
- I2C interface for ASIC control
- Integrated CPU for ADC calibration
- Integrated temperature sensor



# Raw ADC Data Output

Mode	JESD 204B lanes	ADC per lane	Lane data rate	ADC data rate
Full speed	16	2	6.4Gbps	200MS/s
Half speed	8	4	6.4Gbps	100MS/s
Quarter speed	4	8	6.4Gbps	50MS/s

- Programmable ADC sampling rate of 200/100/50 MS/s
- Constant JESD204B output data rate of 6.4Gbps
- Shared JESD204B output data interface between 2/4/8 ADCs reduces the number of interface lines, allowing high system integration density



# ADC Power Consumption

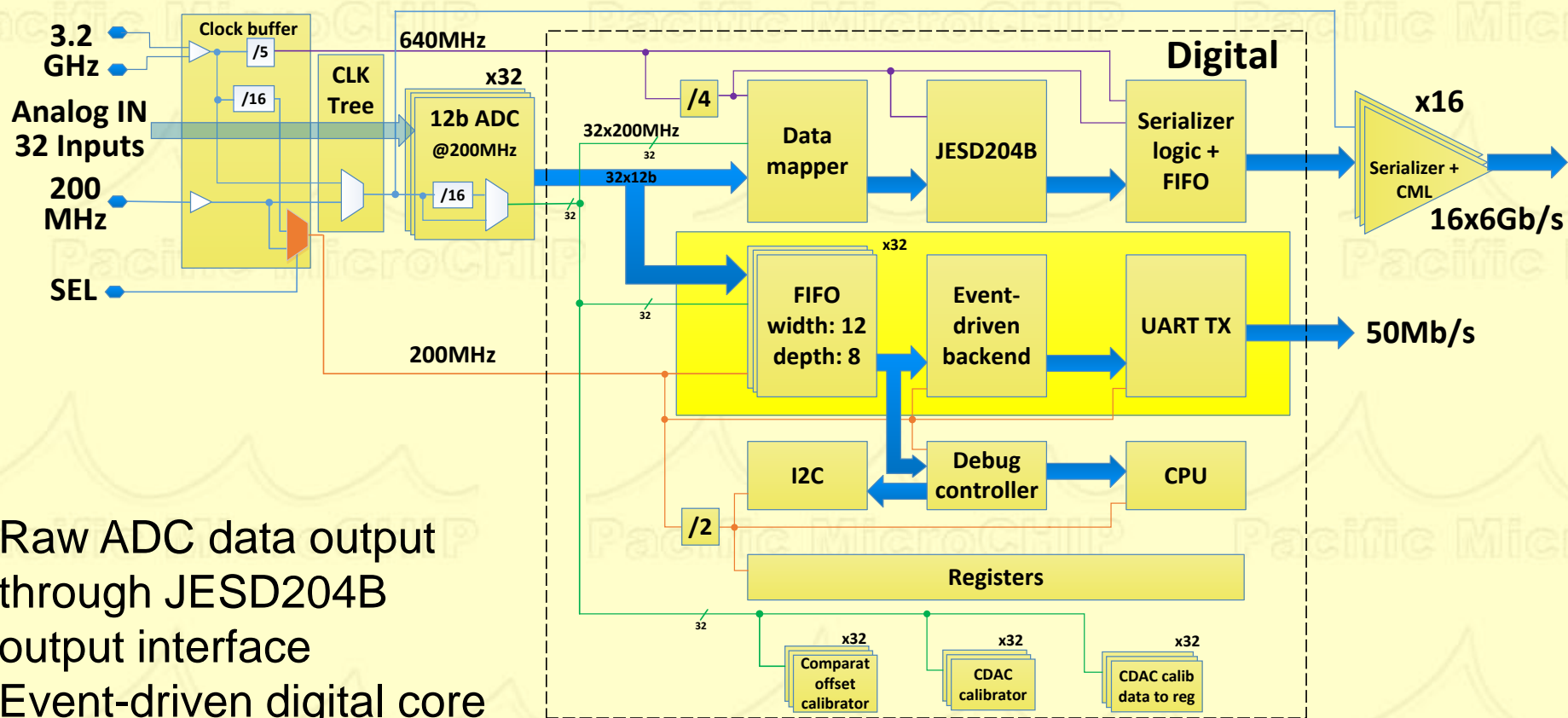
Block	Analog supply current, mA @ 0.9V	Digital supply current, mA @ 0.9V	I/O supply current, mA @ 1.2V	Ground, mA @ 0V
ADC CHANNEL	1.65	7.82	14.88	25.03
ADC CORE 12b@200Msps	1.46	1.62	N/A	3.73
JESD204B PHY	N/A	4.58	14.88	19.48

Typical power consumption of ADC w/o DATA interface: **5mW / ch**

Typical power consumption of ADC with DATA interface: **15.7mW / ch**

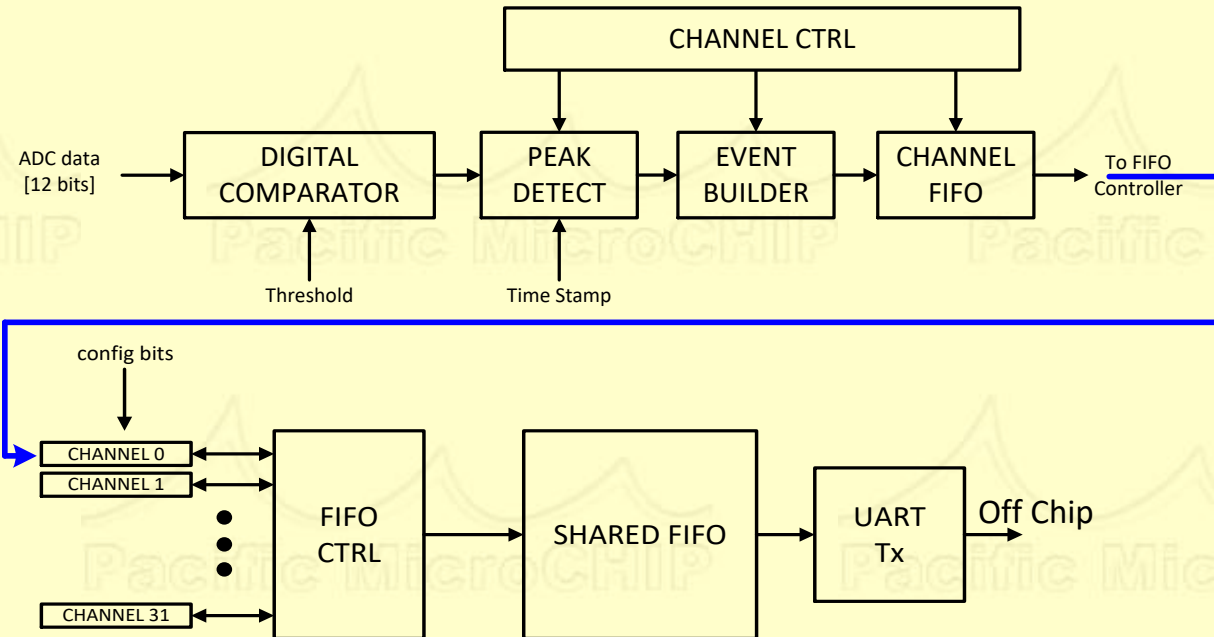
*(One JESD204B output data lane used per 2 ADCs operates at 200Msps)*

# Digital Part



- Raw ADC data output through JESD204B output interface
- Event-driven digital core output through UART interface
- I2C interface for ASIC control registers programming
- Built-in calibration FSM / CPU for calibration purposes

# Event-Driven Digital Back-end



***Event-driven digital back-end was built in collaboration with the LBNL. We want to thank Dr. Carl Grace for his efforts.***

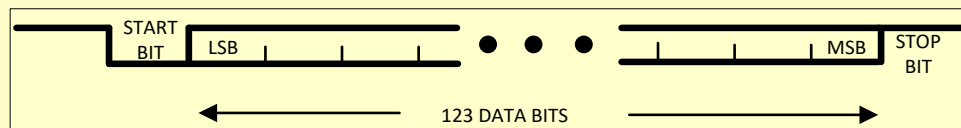
- This ADC output is monitored by a digital comparator with a programmable threshold

- When the ADC input exceeds threshold, a timestamp is assigned, and the peak value of the incoming ADC data is recorded.

- When the event is completed, the relevant information is assembled into a packet at the block's back-end. When the shared FIFO is ready, events stored in the channel FIFO are read out.

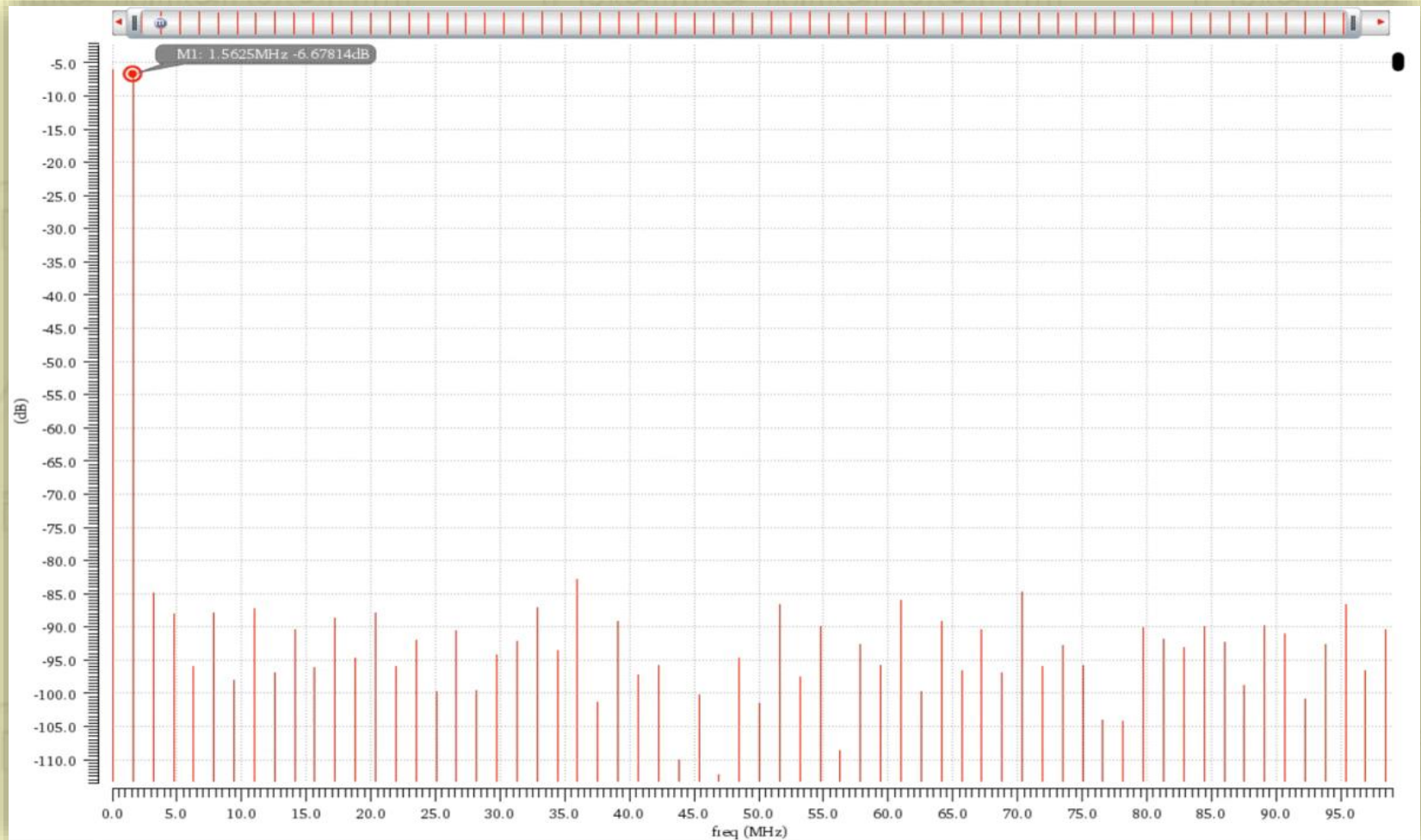
# Output Data Frame

Bits	Field Name	Comment
[123]	Parity	Used to monitor integrity of data transmission.
[122]	Event Declaration	0 → test event (see text), 1 → normal
[121:109]	Window Interval	Determines the number of ADC samples to examine looking for a peak.
[108:104]	Channel ID	5-bit unique identifier.
[103:56]	TOA (Time of Arrival)	The timestamp of where the ADC value passed the threshold. Covers ~16 days at a 200 MHz clock rate.
[55:44]	TOP (Time of peak)	Supports shaper peaking times of up to 20 $\mu$ s at a 200 MHz clock rate.
[43:32]	TOT (Time over Threshold)	Supports shaper pulse widths of up to 40 $\mu$ s at a 200 MHz clock rate.
[31:20]	Peak Value	12-bit peak value recorded in the event.
[19:8]	Channel Threshold	12-bit threshold value used during this event.
[7:6]	Channel FIFO usage	For diagnostics and debugging.
[5:0]	Shared FIFO usage	For diagnostics and debugging.



50Mbps / 124bit / 32ch  
 $\approx$  12.6k/s events per channel

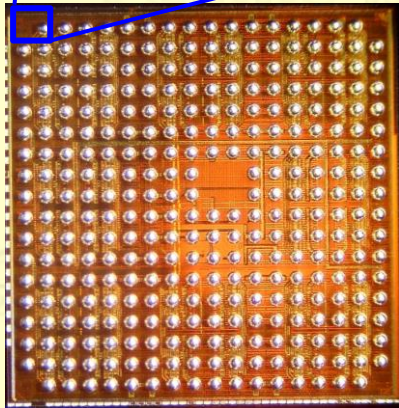
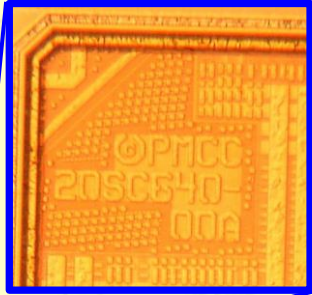
# ADC Output Spectrum vs. Input Signal Frequency (Simulated)



Typical performance: **SFDR > 74dB**, **ENOB > 10.4-bit** for  $F_{in} < 100\text{MHz}$



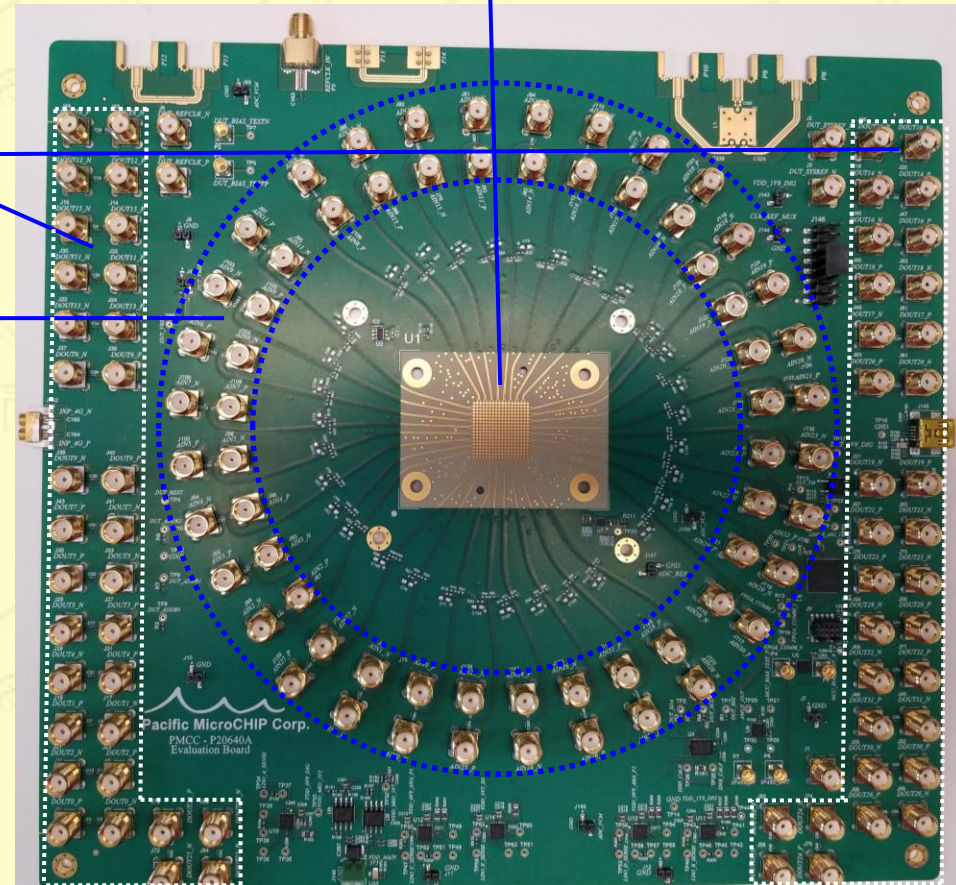
# Chip, Assembled Part, Test Board



ADC direct  
output

Analog  
inputs

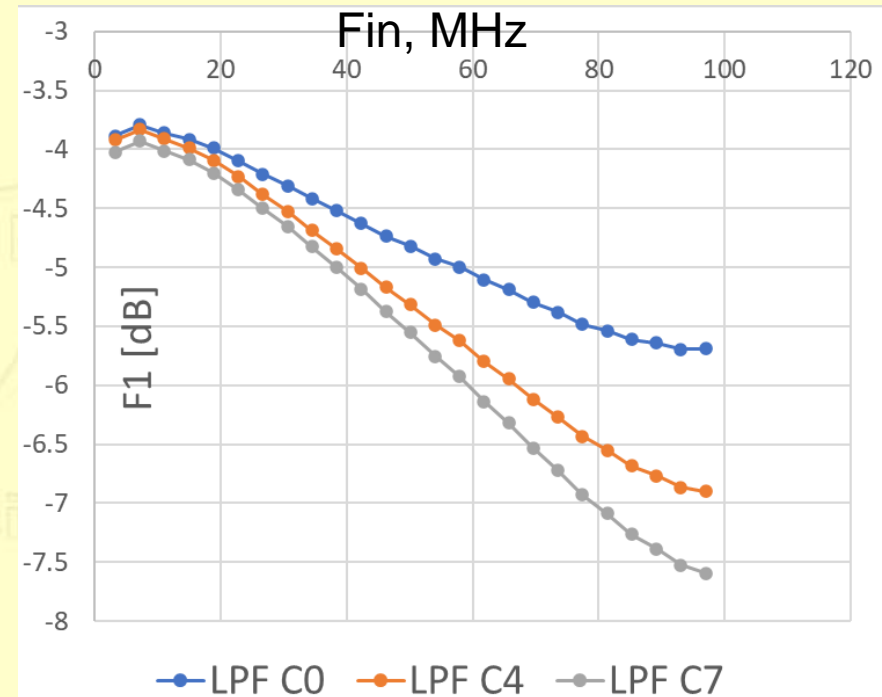
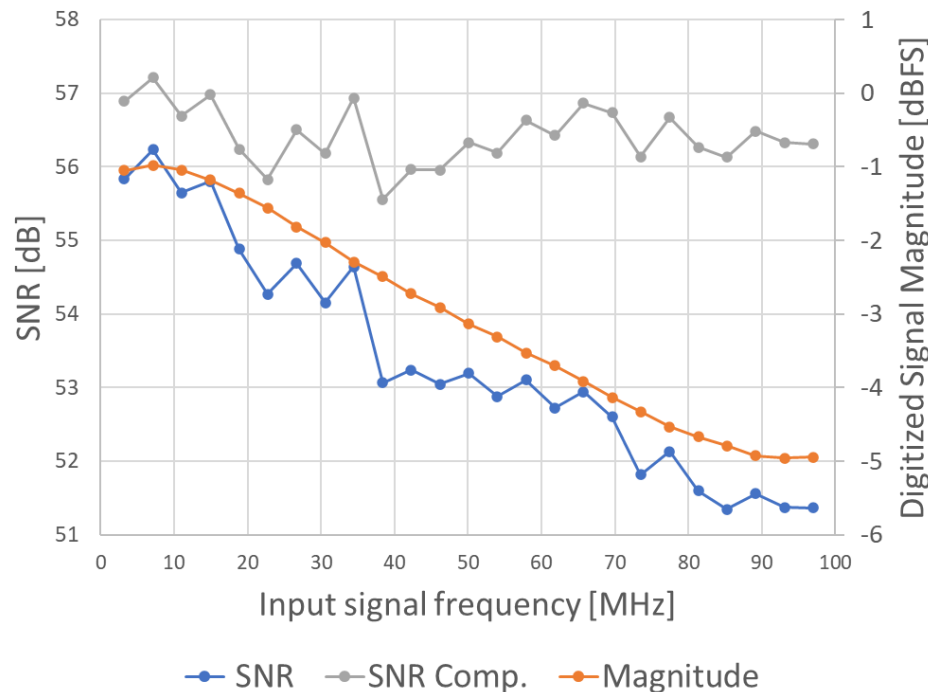
Area for DUT socket



# Preliminary Testing Results

**SNR within 56dB to 57dB => ~9-bit ENOB**  
**Target is >10-bit ENOB**

**BW depending on LPF coefficients:**  
**40MHz to 60MHz @ -1dB**  
**80MHz to >100MHz @ -3dB**





# **Future Plans for ASIC #2**

- **To finish testing the chip's 1<sup>st</sup> prototype (by May'21).**
- **Transition to SBIR Phase IIA or IIB – to redesign the chip, increase its performance, fix issues identified during testing.**
- **To fabricate the final chip.**
- **To test/evaluate it.**
- **To provide the chip to the DoE community and commercial customers.**

# **THANK YOU !**

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**Application ideas for presented ASICs are appreciated!**

**Unanswered questions?**

**Please email: [dalius@pacificmicrochip.com](mailto:dalius@pacificmicrochip.com)**